

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	(("6099678") or ("5138428") or ("6426552") or ("6239012") or ("6255742") or ("6380620") or ("6187611")).PN.	USPAT; USOCR	OR	OFF	2004/10/05 18:13
S2	11112	die adj3 (bond or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 17:56
S3	7888	die adj3 (bond or bonding)and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 08:03
S4	2269	die adj3 (bond or bonding)and semiconductor and base	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 08:03
S5	508	die adj3 (bond or bonding)and semiconductor and base and paste	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 08:04
S6	90	die adj3 (bond or bonding)and semiconductor and base and silver adj paste and (metal or metallic)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 08:46
S7	682	372/36.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 08:18
S8	21	372/36.ccls. and ((die adj3 (bond or bonding)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 08:27
S9	3	372/36.ccls. and ((die adj3 (bond or bonding)) and paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 08:27
S10	579	die adj3 (bond or bonding)and surface adj mount and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 08:48
S11	34	die adj3 (bond or bonding)and surface adj mount adj semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 09:06
S12	83	die adj3 (bond or bonding)and surface adj mount adj3 semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 09:14

S13	10	((("5138428") or ("6140696") or ("6239012") or ("6143590") or ("6417024") or ("5974066") or ("6451628") or ("5977633") or ("6187611") or ("6099678"))).PN.	USPAT; USOCR	OR	OFF	2002/11/06 10:35
S14	17	(US-6451628-\$ or US-6380620-\$ or US-6143590-\$ or US-6064111-\$ or US-6014318-\$ or US-5977633-\$ or US-6284570-\$ or US-6239012-\$ or US-6211462-\$ or US-6187611-\$ or US-6140696-\$ or US-6099678-\$ or US-6417024-\$ or US-5974066-\$ or US-5138428-\$).did. or (US-20010011767-\$).did. or (EP-400177-\$).did.	US-PGPUB; USPAT; DERWENT	OR	OFF	2002/11/06 10:36
S15	1	("0905833").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/11/06 10:36
S16	1	EP000905833A2	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 10:37
S17	18	(US-6451628-\$ or US-6380620-\$ or US-6143590-\$ or US-6064111-\$ or US-6014318-\$ or US-5977633-\$ or US-6284570-\$ or US-6239012-\$ or US-6211462-\$ or US-6187611-\$ or US-6140696-\$ or US-6099678-\$ or US-6417024-\$ or US-5974066-\$ or US-5138428-\$).did. or (US-20010011767-\$).did. or (EP-905833-\$).did. or (EP-400177-\$).did.	US-PGPUB; USPAT; EPO; DERWENT	OR	OFF	2002/11/06 16:08
S18	11677	base and solder and heating	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 16:09
S19	3987	372/36,45.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 16:10
S20	101	die adj3 (bond or bonding)and semiconductor and base and silver adj paste	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 16:10
S21	3	372/36,45.ccls. and ((die adj3 (bond or bonding)and semiconductor and base and silver adj paste))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2002/11/06 16:12

S22	2	("5214660").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/11/06 16:12
S23	6	((("5214660") or ("6047084") or ("5963695"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/11/06 16:13
S24	19	((("5214660") or ("6047084") or ("5963695") or ("6087621") or ("4357072") or ("5673350") or ("6246787") or ("6292499") or ("5966459") or ("6434264"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/11/06 16:14
S25	23	(US-6451628-\$ or US-6380620-\$ or US-6143590-\$ or US-6064111-\$ or US-6014318-\$ or US-5977633-\$ or US-6284570-\$ or US-6239012-\$ or US-6211462-\$ or US-6187611-\$ or US-6140696-\$ or US-6099678-\$ or US-6417024-\$ or US-5974066-\$ or US-5138428-\$ or US-6349104-\$ or US-6047084-\$).did. or (US-20010011767-\$ or US-20020041612-\$ or US-20020105985-\$).did. or (EP-905833-\$).did. or (EP-400177-\$ or GB-2331362-\$).did.	US-PGPUB; USPAT; EPO; DERWENT	OR	OFF	2002/11/06 17:19
S26	1	((US-6451628-\$ or US-6380620-\$ or US-6143590-\$ or US-6064111-\$ or US-6014318-\$ or US-5977633-\$ or US-6284570-\$ or US-6239012-\$ or US-6211462-\$ or US-6187611-\$ or US-6140696-\$ or US-6099678-\$ or US-6417024-\$ or US-5974066-\$ or US-5138428-\$ or US-6349104-\$ or US-6047084-\$).did. or (US-20010011767-\$ or US-20020041612-\$ or US-20020105985-\$).did. or (EP-905833-\$).did. or (EP-400177-\$ or GB-2331362-\$).did.) and (electrical and die\$bond adj paste and metal)	US-PGPUB; USPAT; EPO; DERWENT	OR	OFF	2002/11/06 17:20

S27	1	((US-6451628-\$ or US-6380620-\$ or US-6143590-\$ or US-6064111-\$ or US-6014318-\$ or US-5977633-\$ or US-6284570-\$ or US-6239012-\$ or US-6211462-\$ or US-6187611-\$ or US-6140696-\$ or US-6099678-\$ or US-6417024-\$ or US-5974066-\$ or US-5138428-\$ or US-6349104-\$ or US-6047084-\$).did. or (US-20010011767-\$ or US-20020041612-\$ or US-20020105985-\$).did. or (EP-905833-\$).did. or (EP-400177-\$ or GB-2331362-\$).did.) and (electrical and die\$bond adj paste)	US-PGPUB; USPAT; EPO; DERWENT	OR	OFF	2002/11/06 17:49
S28	4	((US-6451628-\$ or US-6380620-\$ or US-6143590-\$ or US-6064111-\$ or US-6014318-\$ or US-5977633-\$ or US-6284570-\$ or US-6239012-\$ or US-6211462-\$ or US-6187611-\$ or US-6140696-\$ or US-6099678-\$ or US-6417024-\$ or US-5974066-\$ or US-5138428-\$ or US-6349104-\$ or US-6047084-\$).did. or (US-20010011767-\$ or US-20020041612-\$ or US-20020105985-\$).did. or (EP-905833-\$).did. or (EP-400177-\$ or GB-2331362-\$).did.) and (thermal adj4 resistance)	US-PGPUB; USPAT; EPO; DERWENT	OR	OFF	2002/11/06 17:50
S29	4	((US-6451628-\$ or US-6380620-\$ or US-6143590-\$ or US-6064111-\$ or US-6014318-\$ or US-5977633-\$ or US-6284570-\$ or US-6239012-\$ or US-6211462-\$ or US-6187611-\$ or US-6140696-\$ or US-6099678-\$ or US-6417024-\$ or US-5974066-\$ or US-5138428-\$ or US-6349104-\$ or US-6047084-\$).did. or (US-20010011767-\$ or US-20020041612-\$ or US-20020105985-\$).did. or (EP-905833-\$).did. or (EP-400177-\$ or GB-2331362-\$).did.) and (thermal adj4 resistance)	US-PGPUB; USPAT; EPO; DERWENT	OR	ON	2002/11/06 17:52
S30	392	semiconductor adj4 thermal adj4 resistance	US-PGPUB; USPAT; EPO; DERWENT	OR	ON	2002/11/06 17:54
S31	40	semiconductor adj4 thermal adj4 resistance and paste	US-PGPUB; USPAT; EPO; DERWENT	OR	ON	2002/11/06 17:54

S32	25	(US-6451628-\$ or US-6143590-\$ or US-6380620-\$ or US-6349104-\$ or US-6064111-\$ or US-5977633-\$ or US-6014318-\$ or US-5974066-\$ or US-6211462-\$ or US-6187611-\$ or US-6239012-\$ or US-6284570-\$ or US-6140696-\$ or US-6099678-\$ or US-6417024-\$ or US-5138428-\$ or US-6047084-\$ or US-6225694-\$ or US-6086990-\$).did. or (US-20020105985-\$ or US-20020041612-\$ or US-20010011767-\$).did. or (EP-905833-\$).did. or (EP-400177-\$ or GB-2331362-\$).did.	US-PGPUB; USPAT; EPO; DERWENT	OR	OFF	2002/12/16 13:52
S33	13	((("6438149") or ("20020119601") or ("20020062919") or ("20020043728") or ("20020032280") or ("6528169") or ("5372833") or ("6400738") or ("20010011732") or ("6395124") or ("6426552") or ("20020140086") or ("20020028599")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/03/10 12:53
S34	9209	silver near3 paste	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 12:56
S35	394	(silver near3 paste) and (thermal near3 resistance)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 12:57
S36	187	(silver near3 paste) and (thermal near3 resistance) and (mount or mounting)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:01
S37	101	(silver near3 paste) and (thermal near3 resistance) and (mount or mounting) and degree	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:03
S38	0	(silver near3 paste) and (thermal near3 resistance) and (mount or mounting) and ("90.degree" adj3 C)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/06/08 14:17
S39	12	(silver near3 paste) and (thermal near3 resistance) and (mount or mounting) and ("90.degree")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:19
S40	0	Thermal near3 resistance and ("degree" adj3 C adj3 W)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:21

S41	0	".degree" adj3 C adj3 W	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:21
S42	146	degree adj3 C adj3 W	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:22
S43	63	(degree adj3 C adj3 W) and (thermal adj3 resistance)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:22
S44	10	(degree adj3 C adj3 W) and (thermal adj3 resistance) and (silver)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:23
S45	13	(degree adj3 C adj3 W) and (thermal adj3 resistance) and (silver adj3 paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2003/03/10 13:23
S46	2	((("6255742") or ("5138428"))).PN.	USPAT; USOCR	OR	OFF	2004/03/04 13:39
S47	2	((("6328482") or ("5115441"))).PN.	USPAT; USOCR	OR	OFF	2004/03/04 14:42
S48	745	372/36.ccls.	US-PGPUB; USPAT; EPO; DERWENT	OR	ON	2004/06/08 14:12
S49	35	372/36.ccls. and (cure or curing)	US-PGPUB; USPAT; EPO; DERWENT	OR	ON	2004/06/08 14:14
S50	25	372/36.ccls. and ((cure or curing) and step)	US-PGPUB; USPAT; EPO; DERWENT	OR	ON	2004/06/08 14:14
S51	245	(silver near3 paste) and (thermal near3 resistance) and (mount or mounting)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/06/08 14:14
S52	31	(silver near3 paste) and (thermal near3 resistance) and (mount or mounting) and (degree near3 C)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/06/08 14:15
S53	475	semiconductor adj4 thermal adj4 resistance	US-PGPUB; USPAT; EPO; DERWENT	OR	ON	2004/06/08 14:15

S54	122	(bond or bonding)and semiconductor and base and (silver adj paste) and (cure or curring)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/06/08 14:17
S55	145	(silver near3 paste) and (thermal near3 resistance) and (mount or mounting) and degree	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/06/08 14:17
S56	1039	257/780.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/06/08 14:19
S57	86	257/780.ccls. and (semiconductor and (cure or curring))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/06/08 14:48
S58	7	((("6255742") or ("6426552") or ("5138428") or ("6099678") or ("6187611") or ("6380620") or ("6239012"))).PN.	USPAT; USOCR	OR	OFF	2004/06/08 14:49
S59	0	((("temporarynear3cure)and(finalnear3curing"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/06/10 09:01
S60	12	(temporary near3 (cure or curing))and(final near3 (cure or curing))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2004/06/10 09:01
S61	1	("4775439").PN.	USPAT; USOCR	OR	OFF	2004/06/14 11:00
S66	7	((("6099678") or ("5138428") or ("6426552") or ("6239012") or ("6255742") or ("6380620") or ("6187611"))).PN.	USPAT; USOCR	OR	OFF	2005/06/01 15:54
S67	44	semiconductor and ((die near3 bond near3 paste) and metal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 17:57
S68	31	semiconductor and ((die near3 bond near3 paste) and metal) and thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 17:58
S69	0	semiconductor and ((die near3 bond near3 paste) and (metal adj3 filler)) and thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 17:58
S70	1	semiconductor and ((die near3 bond near3 paste) and (metal adj3 filler))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 17:58

S71	3	semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 17:59
S72	1	semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:18
S73	0	257/780.ccls. and (semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:18
S74	0	257/706.ccls. and (semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:18
S75	0	257/667.ccls. and (semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:18
S76	0	438/122.ccls. and (semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:19
S77	0	438/612.ccls. and (semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:19
S78	0	"438"/\$\$\$ccls. and (semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:19
S79	0	"257"/\$\$\$ccls. and (semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:19
S80	1	"372"/\$\$\$ccls. and (semiconductor and ((die near3 bond near3 paste) and (metal adj3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:20
S81	1	"438"/\$\$\$ccls. and (semiconductor and ((bond near3 paste) and (metal near3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:20

S82	6	"257"/\$\$\$\$.ccls. and (semiconductor and ((bond near3 paste) and (metal near3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:31
S83	0	257/659.ccls. and (semiconductor and ((bond near3 paste) and (metal near3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:32
S84	1	257/724.ccls. and (semiconductor and ((bond near3 paste) and (metal near3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:32
S85	0	257/197.ccls. and (semiconductor and ((bond near3 paste) and (metal near3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:32
S86	1	257/706.ccls. and (semiconductor and ((bond near3 paste) and (metal near3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:32
S87	0	257/625.ccls. and (semiconductor and ((bond near3 paste) and (metal near3 bond\$4)) and thick\$4 and (therm\$4 adj3 resist\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/06/14 18:32